



20k=20ns Deadtime  
 65k=10ns Deadtime  
 158k=5ns Deadtime

0.6V@10A  
 0.8V@10A

0.6V@10A  
 0.8V@10A

Orderable: <a href="#">ChangeMe!</a>	Designed for:	Mod. Date: 5/1/2018
TID #: N/A	Project Title: GaN and Si Power Board	
Number: PMP21440	Rev: A	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 1
Drawn By:	File: PMP21440 Power Board_BlankSheet.SchDoc	Size: B
Engineer: Jose Ramirez	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	

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